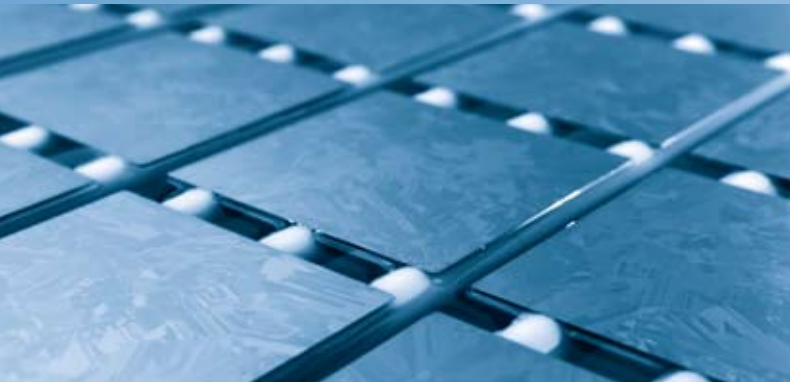


# SOLAR InPolish

R|E|N|A|.



## Inline single side polishing

The InPolish system smoothens one side of the wafer using a polishing etch in an inline single side process. Thus it provides the smooth surface required for high-efficiency concepts like rear-side passivated cells, improves the back side reflection and allows for an efficient passivation of the rear surface. Together with the InOxSide® tool, it completes RENA's toolbox for rear-side passivated cells.

### Areas of application

- Single side polish etching for high efficiency solar cells
- Designed for multi- and monocrystalline wafers
- Wafer transfer systems available for automatic loading and unloading

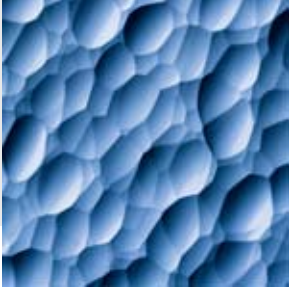
### Features and benefits

- Enables processing schemes for rear-side passivated cells
- Inline single side process:
  - Straight line footprint
  - Ideal process and work flow integration
- Suitable for both multi- and monocrystalline cells
- Technological leadership
- Process start up by RENA
- Etch depth and polishing grade tunable to the cell requirements

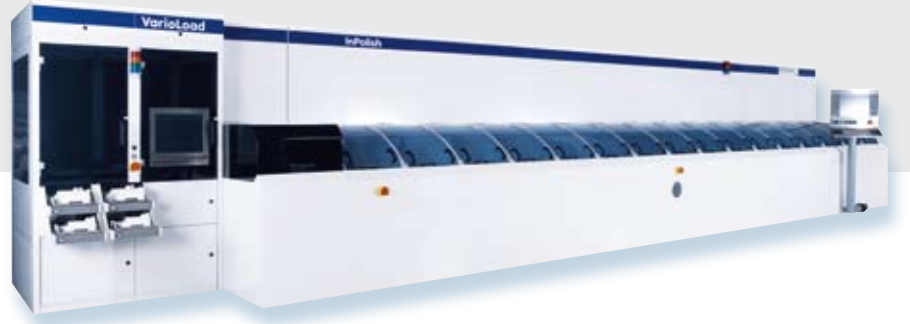




Polished monocrystalline cell



Polished multicrystalline cell



Front view InPolish

## Technical Data InPolish

	InPolish HT
Platform	NIAK 5 lanes for 156 mm wafers
Process	Single side polish etching for high efficiency solar cells
Dimensions	9600 x 2150 x 2350 mm (length x width x height)
Throughput	3600 wafers/h gross *) wafer size 156 mm
Wafer thickness	> 150 $\mu\text{m}$
Etch depth	$\leq 10 \mu\text{m}$ *)

\*) Tool with reduced throughput and/or higher etch depth available upon request.

## Polishing examples

